MA4X193 (MA193)

Silicon epitaxial planar type

For switching circuit

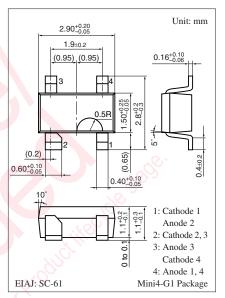
■ Features

- Four isolated elements contained in one package
- Short reverse recovery time t_{rr}
- Bridge diodes for surface mounting
- Anode common + cathode common composite product

■ Absolute Maximum Ratings $T_a = 25$ °C

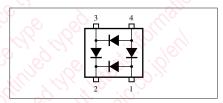
Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	80	V
Repetitive peak reverse voltage	V_{RRM}	80	V
Forward current (Average)	I _{F(AV)}	70	mA
Repetitive peak forward current	I _{FRM}	150	mA
Non-repetitive peak forward surge current *	I_{FSM}	250	mA
Junction temperature	T _j	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

Note) *: t = 1 s



Marking Symbol: M2Z

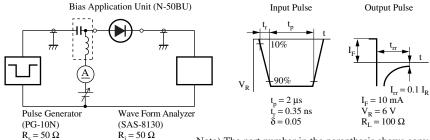
Internal Connection



■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

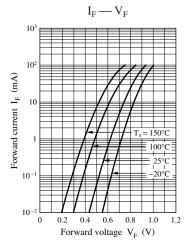
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{\rm F}$	$I_F = 70 \text{ mA}$	1.90		1.2	V
Reverse voltage	V_R	$I_R = 100 \mu A$	80			V
Reverse current	I_R	V _R = 75 V			100	nA
Terminal capacitance	C _t	$V_R = 0 V, f = 1 MHz$			15	pF
Reverse recovery time *	t _{rr}	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$			10	ns
"VSI		$I_{rr} = 0.1 I_R$, $R_L = 100 \Omega$				

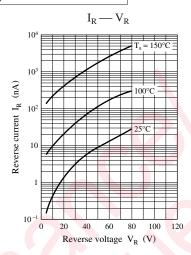
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 - 2. Absolute frequency of input and output is 100 MHz.
 - 3. *: t_{rr} measurement circuit

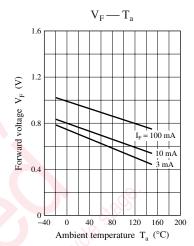


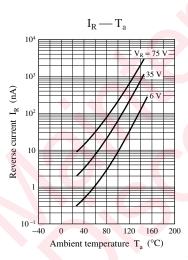
Note) The part number in the parenthesis shows conventional part number.

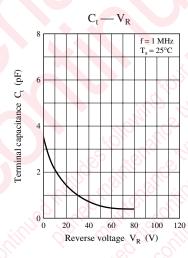
4-1 and 4-3 pins (anode common) characteristics charts

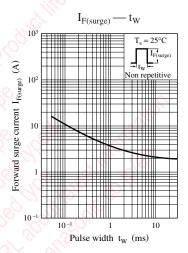






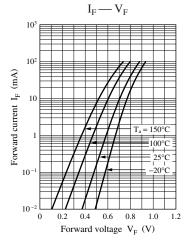


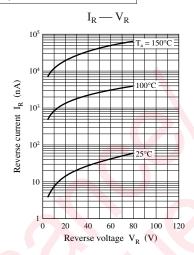


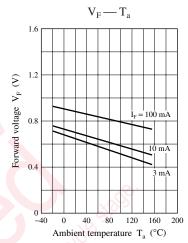


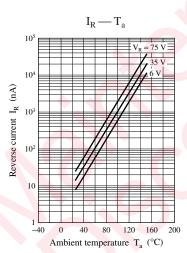
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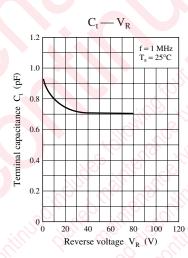
1-2 and 3-2 pins (cathode common) characteristics charts

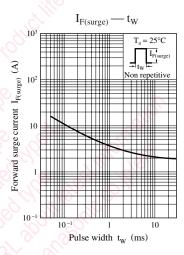












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